

09-07-2004



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To the Director of the U.S. Patent and Trad.

ts or the new address(es) below.

1. Name of conveying party(ies)/Execution Date(s):

Hisashi Tanie

Execution Date(s) April 12, 2004

Additional name(s) of conveying party(ies) attached? ☒ Yes ☐ No

3. Nature of conveyance:

- ☒ Assignment ☐ Merger  
☐ Security Agreement ☐ Change of Name  
☐ Government Interest Assignment  
☐ Executive Order 9424, Confirmatory License  
☐ Other

2. Name and address of receiving party(ies)

Name: Hitachi, Ltd.

Internal Address:

Street Address: 6, Kanda Surugadai 4-chome,  
Chiyoda-ku

City: Tokyo

State:

Country: Japan

Zip:

Additional name(s) & address(es) attached? ☒ Yes ☐ No

4. Application or patent number(s):

☐ This document is being filed together with a new application.

A. Patent Application No.(s)

10/836,098

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address to whom correspondence concerning document should be mailed:

Name: Robert C. Colwell

Internal Address:

TOWNSEND AND TOWNSEND AND CREW LLP

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6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00

- ☐ Authorized to be charged by credit card  
☒ Authorized to be charged to deposit account  
☐ Enclosed  
☐ None required (government interest not affecting title)

8. Payment Information

a. Credit Card Last 4 numbers  
Expiration Date

b. Deposit Account Number 20-1430

Authorized User Name

9. Signature:

Robert C. Colwell

Name of Person Signing Atty. Reg. No. 27,431

Total number of pages including cover sheet, attachments, and documents:

Documents to be recorded (including cover sheet) should be faxed to (703) 306-5995, or mailed to:  
Mail Stop Assignment Recordation Services, Director of the USPTO, P.O.Box 1450, Alexandria, VA 22313-1450

09/03/2004 MGETACHE 00000150 201430 10836098

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1. Additional name(s) of conveying party(ies):  
(Continued from Page 1)

Nae Hisano  
Koji Hosokawa

2. Additional name(s) and address(es) of receiving party(ies):  
(Continued from Page 1)

Elpida Memory, Inc.  
2-1, Yaesu 2-chome, Chuo-ku  
Tokyo, Japan

3. Additional application number(s) or patent number(s):  
(Continued from Page 1)

A. Patent Application No.(s)

B. Patent No.(s)

60293371 v1

10/836,098

W/648-01  
(\*)**ASSIGNMENT**  
( 譲 渡 証 )

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to Hisashi TANIE, Nae HISANO, and Koji HOSOKAWA, citizens of Japan by HITACHI, LTD., and Elpida Memory, Inc., corporations organized under the laws of Japan, located at 6, Kanda Surugadai 4-chome, Chiyoda-ku, Tokyo, Japan, and 2-1, Yaesu 2-chome, Chuo-ku, Tokyo, Japan, respectively, receipt of which is hereby acknowledged, we, the said Hisashi TANIE, Nae HISANO, and Koji HOSOKAWA, do hereby sell and assign to said HITACHI, LTD., and Elpida Memory, Inc., their successors and assigns, all our right, title and interest, in and for the United States of America, in and to

**SEMICONDUCTOR MODULE**

invented by us and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said HITACHI, LTD., and Elpida Memory, Inc., their successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by us if this assignment and sale had not been made;

And we hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of said above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And we do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI, LTD., and Elpida Memory, Inc.

Signed on the date(s) indicated aside signatures:

INVENTOR(S)  
(発明者フルネームサイン)

Date Signed  
(署名日)

1) <u>Hisashi Tanie</u>	<u>4/12/04</u>
2) <u>Nae Hisano</u>	<u>4/12/04</u>
3) <u>Koji Hosokawa</u>	<u>4/15/04</u>
4) _____	_____
5) _____	_____
6) _____	_____
7) _____	_____
8) _____	_____
9) _____	_____
10) _____	_____